PMP10886 REVA BOM.xlsx
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1/30/2015

PMP10886 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	Package
C1, C2, C3, C7, C10	5	10uF	C3225X7R1E106M250AC	TDK	CAP, CERM, 10uF, 25V, +/-20%, X7R, 1210	1210
C4, C9	2	150uF	EEE-FK1E151P	Panasonic	CAP, AL, 150uF, 25V, +/-20%, 0.16 ohm, SMD	SMT Radial F
C5, C6	2	180uF	25SVPF180M	Sanyo	CAP, OS-CON, 180uF, 25V, 4.65Arms, 0.016 ohm, E12	8x10
C8	1	1uF	C2012X7R1E105K	TDK	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0805	0805
C11, C19	2	0.47uF	GRM188R71E474KA12D	MuRata	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603
C12, C13	2	1000pF	GRM188R71H102KA01D	MuRata	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	0603
C14	1	3.3uF	C3216X7R1H335K160AC	TDK	CAP, CERM, 3.3uF, 50V, +/-10%, X7R, 1206	1206
C15	1	1uF	C1608X7R1E105K	TDK	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603
C16	1	0.033uF	C1608X7R1H333K	TDK	CAP, CERM, 0.033uF, 50V, +/-10%, X7R, 0603	0603
C17	1	100pF	C1608C0G1H101J	TDK	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603
C18	1	0.1uF	C1608X7R1H104K	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
C20	1	10uF	C3216X7R1E106K	TDK	CAP, CERM, 10uF, 25V, +/-10%, X7R, 1206	1206
D1, D2	2	60V	PMEG6010CEH	NXP	Diode, Schottky, 60V, 1A, SOD-123F	SOD-123F
H1, H2	2		ELDE 0553_10	Harting	Han Fast Lock Codierung, TH	Han Fast Lock Codierung, TH
J1, J2	2		ED120/2DS	On-Shore	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
J3	1		PEC03SAAN	Sullins	Header, 100mil, 3x1, Tin, TH	Header, 3 PIN, 100mil, Tin
J4, J5, J6, J7	4		09 08 000 6124	Harting	Power Connector, 8AWG, SILVER W/PIN, TH	10x16.65mm
H1, H2	2		ELDE 0553_10	Harting	Han Fast Lock Codierung, Lock Ring, TH	
L1	1				Coupled inductor, 12 µH	1030mmx1050mm
L2	1	22uH	SER2918H-223KL	Coilcraft	Inductor, Shielded E Core, Ferrite, 22uH, 15A, 0.0026 ohm, SMD	SER2918
L3	1	22uH	SER1390-223MLB	Coilcraft	Inductor, SMT, Ferrite, 22uH, 7.36A, 0.021 ohm, SMD	13.5x9.0x13.5mm
Q1, Q2	2	40V	CSD18504Q5A	Texas Instruments	MOSFET, N-CH, 40V, 15A, SON 5x6mm	SON 5x6mm
R1	1	1.00	CRCW12061R00FKEA	Vishay-Dale	RES, 1.00 ohm, 1%, 0.25W, 1206	1206
R2	1	0.003	ERJ-M1WSF3M0U	Panasonic	RES, 0.003, 1%, 1 W, 2512	2512
R3	1	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00k ohm, 1%, 0.1W, 0603	0603
R4, R10	2	49.9k	CRCW060349K9FKEA	Vishay-Dale	RES, 49.9k ohm, 1%, 0.1W, 0603	0603
R5, R6	2	100	ERJ-3GEY0R00V	Panasonic	RES, 0 ohm, 5%, 0.1W, 0603	0603
R7	1	3.3	CRCW06033R30JNEA	Vishay-Dale	RES, 3.3 ohm, 5%, 0.1W, 0603	0603
R8	1	14.0k	CRCW060314K0FKEA	Vishay-Dale	RES, 14.0 k, 1%, 0.1 W, 0603	0603
R9	1	21.5k	CRCW060321K5FKEA	Vishay-Dale	RES, 21.5k ohm, 1%, 0.1W, 0603	0603
R11	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
R12	1	40.2k	CRCW060340K2FKEA	Vishay-Dale	RES, 40.2 k, 1%, 0.1 W, 0603	0603
R13	1	60.4k	CRCW060360K4FKEA	Vishay-Dale	RES, 60.4 k, 1%, 0.1 W, 0603	0603

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R14	1	5.49k	CRCW06035K49FKEA	Vishay-Dale	RES, 5.49 k, 1%, 0.1 W, 0603	0603
TP1, TP2, TP3, TP4, TP7	5	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP5, TP6, TP8	3	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		LM5122MH/NOPB	Texas Instruments	Wide Input Synchronous Boost Controller with Multiple Phase Capability, PWP0020A	PWP0020A

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